

## 7<sup>th</sup> IEEE Electron Devices Technology and Manufacturing (EDTM) Conference 2023

March 7 - 10, 2023 / COEX Seoul, Korea

35A. Power Devices and Widebandgap Heterostructures (2)		
Session Date:	March 9(Thu.), 2023	
Session Time:	14:45-16:20	
Session Room:	Room A (#301)	
Session Chair:	Prof. Hyemin Kang (Korea Institute of Energy Technology)	
	Prof. Wataru Saito (Kyushu University)	
[35A-1] [Invited]		14:45-15:10
Ultrawide Bandgap CMOS Platform for Heterogenous Power Integration		
Saravanan Yuvaraja and Xiaohang Li		
King Abdullah University of Science and Technology		
[35A-2] [Invited]		15:10-15:35
Transfer Printed Power Electronics Based on $\beta$ -Ga <sub>2</sub> O <sub>3</sub> and Diamond Membranes		
Edward Swinnich, Yixiong Zheng, Junyu Lai and Jung-Hun Seo		
The University at Buffalo		
[35A-3]		15:35-15:50
Novel Trench Type Complementary LIGBTs with Common Double Drift Layers for Simple		
Process and Improvement in Switching Characteristics		
Zijian Zhang, Qi Tang, Suyang Liu and Masahide Inuishi		
Waseda University		
[35A-4]		15:50-16:05
The Study of Dislocation Propagation in Si Wafer during IGBT High Thermal Budget Process		
Jiuyang Yuan, Yoshiji Miyamura, Satoshi Nakano, Wataru Saito and Shin-Ichi Nishizawa		
Kyushu University		
[35A-5]		16:05-16:20
Characterization of Oxide Interface Charges in Trench Field Stop IGBT		
Zhi Lin Sim <sup>1,2</sup> , Wei Mien Chin <sup>2</sup> , Yi Xiang Bong <sup>2</sup> , David Goh <sup>2</sup> and Voon Cheng Ngwan <sup>2</sup>		
<sup>1</sup> Nanyang Technological University, <sup>2</sup> STMicroelectronics Inc.		